

ABSTRACT OF THE DISCLOSURE

Disclosed are a lead frame and an electronic component using such a lead frame.

In order to both assure reliability and reduce costs, the lead frame of the present invention

5 comprises a plate-like disk part on which a chip which is a main body of an electronic component is mounted, and a plate-like lead part formed thinner than the disk part and functioning as an electrical external connecting terminal of the electronic component, wherein the disk part and the lead part are joined together by means of ultrasonic welding.